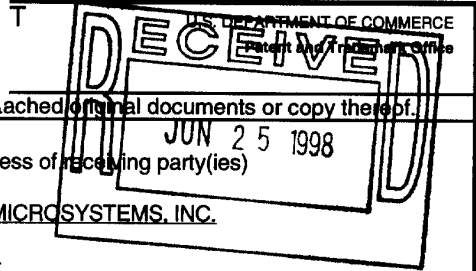


MRP 6-25-98

07-08-1998

FORM PTO-1595 (Rev. 6-93)



OMB No. 0651-0011 (exp. 4/94) To The Honorable Commissioner of Patents

100757036

attached original documents or copy thereof.

1. Name of conveying party(ies): PATKI, Ema WONG, Daniel C. W. Additional name(s) of conveying party(ies) attached? Yes  No

2. Name and address of receiving party(ies) Name: SUN MICROSYSTEMS, INC. Internal Address:

3. Nature of conveyance:  Assignments Merger Security Agreement Change of Name Other Execution Date: March 20, 1998 & May 29, 1998

Street Address: 901 San Antonio Road PAL01-521 City: Palo Alto State: CA Zip: 94303 Additional name(s) & address(es) attached? Yes  No

4. Application number(s) or patent number(s): If this document is being filed together with a new application, the execution date of the application is: A. Patent Application No.(s) 08/958,610 B. Patent No.(s) Additional numbers attached? Yes  No

5. Name and address of party to whom correspondence concerning document should be mailed: Name: HECKER & HARRIMAN Internal Address: 1925 Century Park East, Suite 2300 Los Angeles, California 90067 Street Address: 1925 Century Park East Suite 2300 City: Los Angeles State: CA Zip: 90067

6. Total number of applications and patents involved: 1 7. Total fee (37 CFR 3.41): \$ 40.00 Enclosed Authorized to be charged to deposit account for any deficiency 8. Deposit account number: 08-1520 (Attach duplicate copy of this page if paying by deposit account)

07/06/1998 DMSUYEN 00000257 08958610 01 FC:581 40.00 DP

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9. Statement and signature. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document. J. D. Hariman II Name of Person Signing Reg. No. 31,967

Signature Date 6/19/98

Total number of pages including cover sheet, attachments, and document: 3

Mail documents to be recorded with required cover sheet information to: Commissioner of Patents and Trademarks, Box Assignments Washington, D.C. 20231

PATENT REEL: 9278 FRAME: 0734

**ASSIGNMENT**

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, I, the undersigned, EMA PATKI, hereby sell, assign, and transfer to: SUN MICROSYSTEMS, INC., a corporation of Delaware, having a principal place of business at: 901 San Antonio Road, M/SPAL01-521, Palo Alto, California 94303 ("Assignee") its successors, assigns and legal representatives, the entire right, title and interest for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent

which has been executed by the undersigned concurrently herewith,


which was filed October 27, 1997 and assigned Serial No. 08/958,610

and is entitled: A SELECTABLE DEPACKETIZER ARCHITECTURE and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be issued in the United States and all foreign countries on said improvements; and in and to all rights of priority resulting from the filing of said United States application;

Agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Date: 3/20/98, 1998

  
Name: EMA PATKI

**ASSIGNMENT**

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, I, the undersigned, DANIEL C. W. WONG, hereby sell, assign, and transfer to: SUN MICROSYSTEMS, INC., a corporation of Delaware, having a principal place of business at: 901 San Antonio Road, M/SPAL01-521, Palo Alto, California 94303 ("Assignee") its successors, assigns and legal representatives, the entire right, title and interest for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent

which has been executed by the undersigned concurrently herewith,

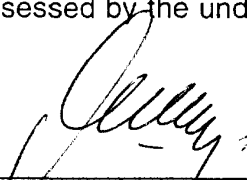
which was filed Oct. 27, 1997 and assigned Serial No. 08/958,610

and is entitled: A SELECTABLE DEPACKETIZER ARCHITECTURE and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be issued in the United States and all foreign countries on said improvements; and in and to all rights of priority resulting from the filing of said United States application;

Agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Date: 5/29/, 1998

  
 Name: DANIEL C. W. WONG